

6EDL04x065xT family

650 V three-phase gate driver with Over Current Protection (OCP), Enable (EN), Fault and Integrated Bootstrap Diode (BSD)

Features

- Infineon thin-film-SOI-technology
- Maximum blocking voltage +650 V
- Output source/sink current +0.165 A / -0.375 A
- Integrated ultra-fast, low $R_{DS(ON)}$ Bootstrap Diode
- Insensitivity of the bridge output to negative transient voltages up to -50 V given by SOI-technology
- Separate control circuits for all six drivers
- Detection of over current and under voltage supply
- Externally programmable delay for fault clear after over current detection
- 'Shut down' of all switches during error conditions
- CMOS and LSTTL compatible input (negative logic)
- Signal interlocking of every phase to prevent cross-conduction

Potential applications

- Home appliance, refrigeration compressors, air-conditioning
- Fans, pumps
- Motor drives, general purpose inverters
- Power tools, light electric vehicles

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Description

The device 6ED family – 2nd generation is a full bridge driver to control power devices like MOS-transistors or IGBTs in 3-phase systems with a maximum blocking voltage of +650 V. Based on the used SOI-technology there is an excellent ruggedness on transient voltages. No parasitic thyristor structures are present in the device. Hence, no parasitic latch-up may occur at all temperatures and voltage conditions.

The six independent drivers are controlled at the low-side using CMOS resp. LSTTL compatible signals, down to 3.3 V logic. The device includes an under-voltage detection unit with hysteresis characteristic and an over-current detection. The over-current level is adjusted by choosing the resistor value and the threshold level at pin ITRIP. Both error conditions (under-voltage and over-current) lead to a definite shut down off all six switches. An error signal is provided at the FAULT open drain output pin. The blocking time after over-current can be adjusted with an RC-network at pin RCIN. The input RCIN owns an internal current source of 2.8 μ A. Therefore, the resistor RRCIN is optional. The typical output current can be given with 165 mA for pull-up and 375 mA for pull down. Because of system safety reasons a 310 ns interlocking time has been realised. The function of input EN can optionally be extended with over-temperature detection, using an external NTC-resistor (see Figure 1). The monolithic integrated bootstrap diode structures between pins VCC and VBx can be used for power supply of the high side.

Product summary

V_{OFFSET}	= 670 V max.
$I_{O+/-}$ (typ.)	= +0.165 A / -0.375 A
t_{on} / t_{off} (6EDL04IxT)	= 530ns / 490 ns
t_{on} / t_{off} (6EDL04NxT)	= 530ns / 530 ns
t_i / t_r (typ. $C_L=1$ nF)	= 60 ns / 26 ns

Package

PG-DSO-28



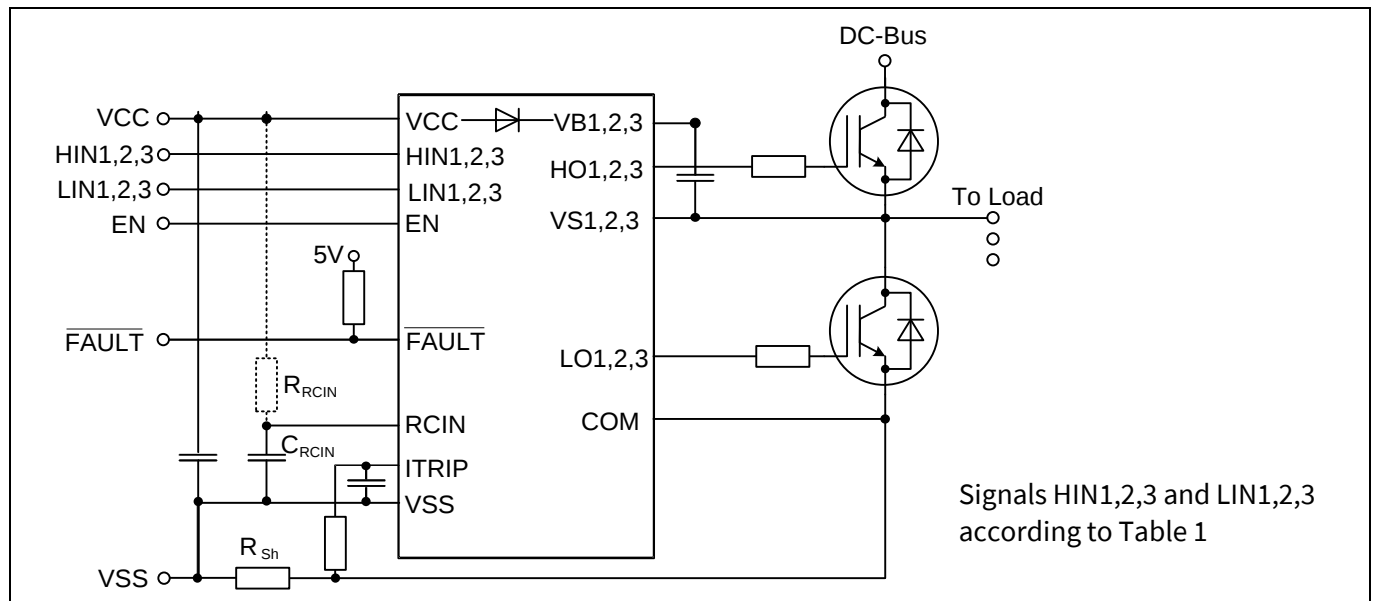


Figure 1 Typical application diagram

Ordering information

Table 1 Members of 6EDL04 family – 2nd generation

Sales Name	Control input HIN and LIN	Target transistor	Typ. UVLO- Thresholds	Bootstrap diode	Package	Orderable part number
6EDL04I065NT	negative logic	IGBT	11.7 V / 9.8 V	Yes	DSO-28	6EDL04I065NTXUMA1
6EDL04I065PT	positive logic	IGBT	11.7 V / 9.8 V	Yes	DSO-28	6EDL04I065PTXUMA1
6EDL04N065PT	positive logic	MOSFET	9 V / 8.1 V	Yes	DSO-28	6EDL04N065PTXUMA1

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1 Block diagram

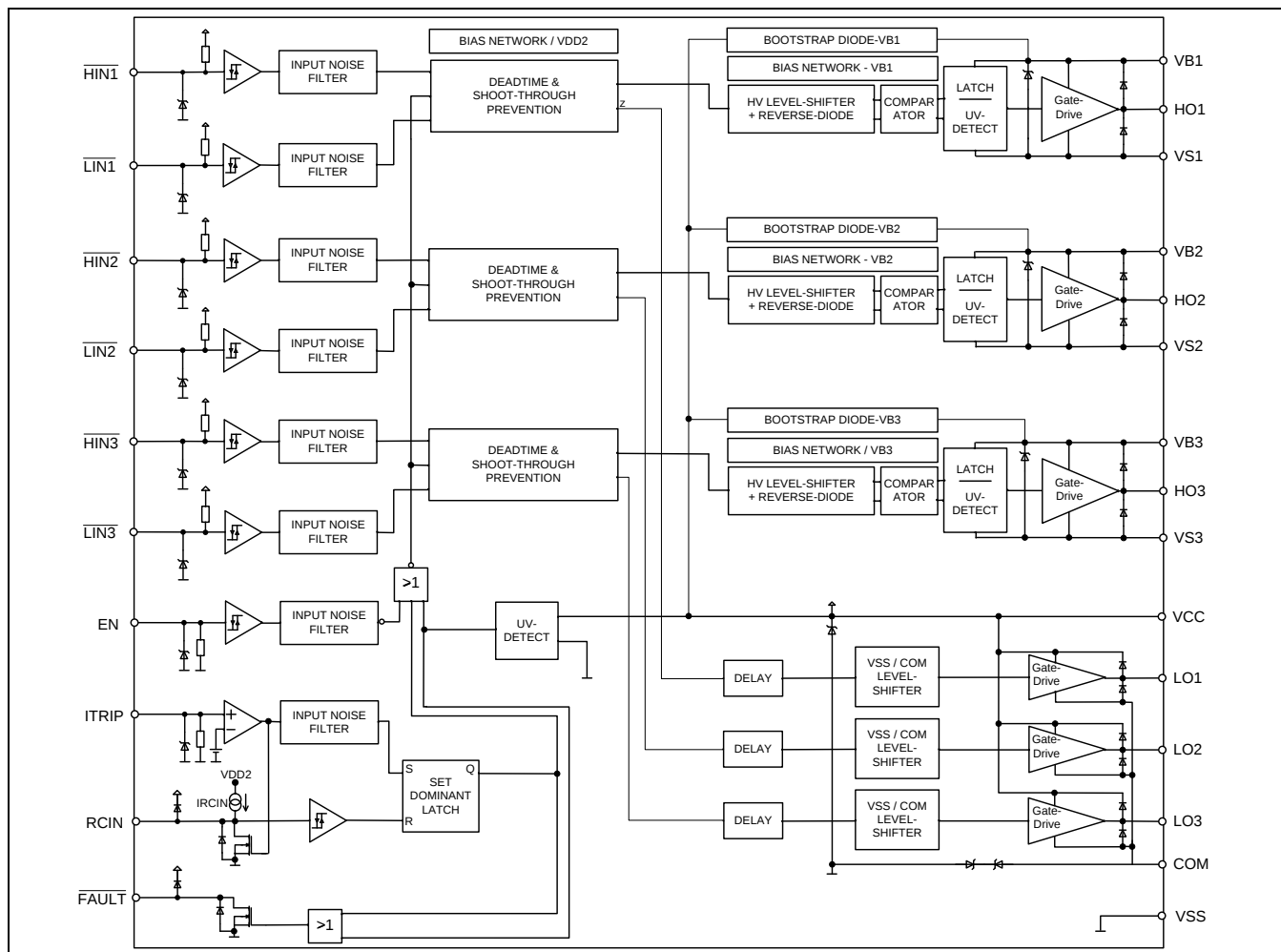


Figure 2 Functional block diagram for 6EDL04I065NT

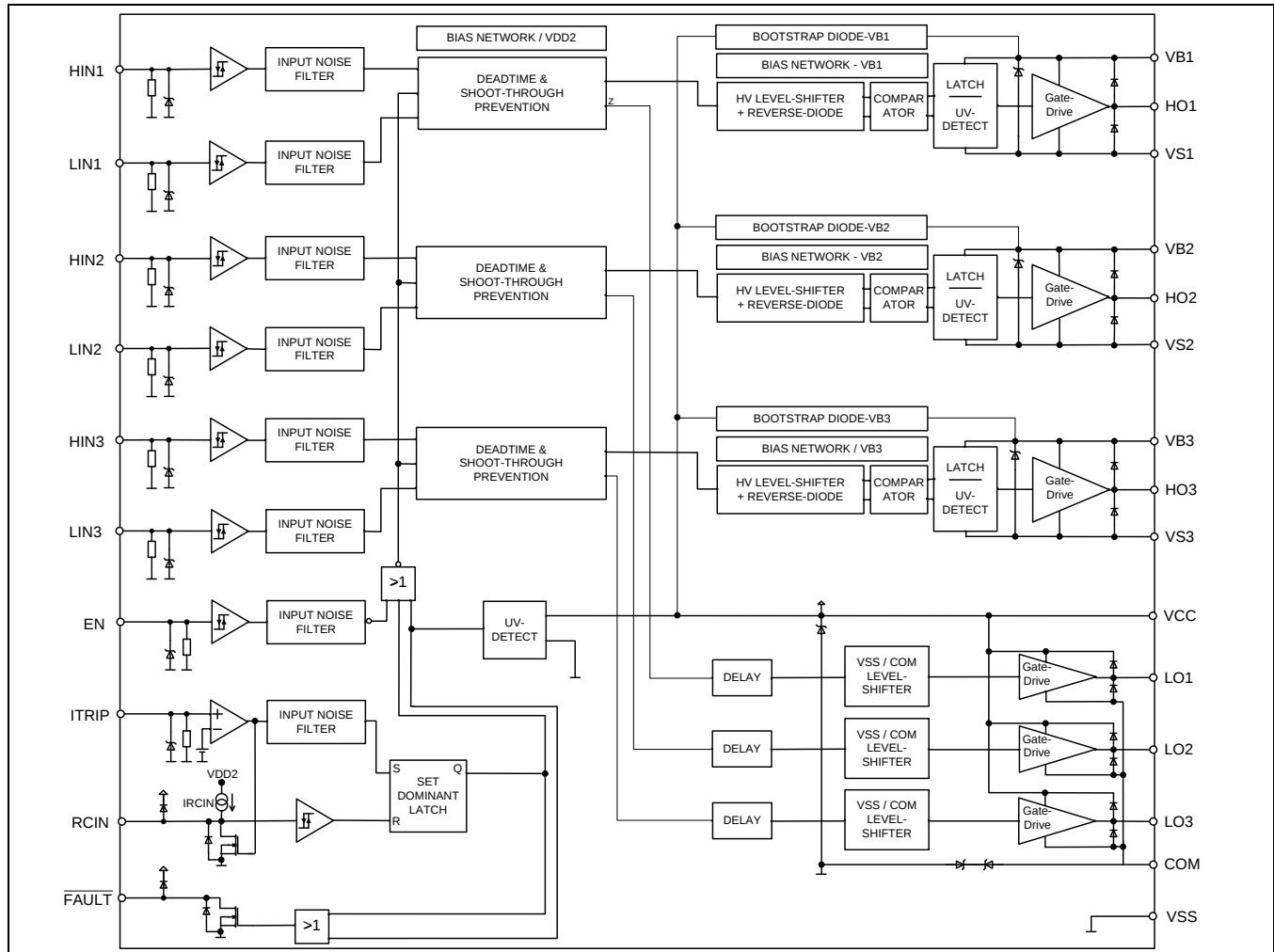


Figure 3 Functional block diagram for 6EDL04I065PT and 6EDL04N065PT

2 Lead definitions

Table 2 6EDL04 family lead definitions

Pin no.	Name	Function
1	VCC	Low side power supply
2,3,4	HIN1,2,3	High side logic input (positive or negative logic according to Table 1)
5,6,7	LIN1,2,3	Low side logic input (positive or negative logic according to Table 1)
8	/FAULT	Indicates over-current and under-voltage (negative logic, open-drain output)
9	ITRIP	Analog input for over-current shut down, activates FAULT and RCIN to VSS
10	EN	Enable I/O functionality (positive logic)
11	RCIN	External RC-network to define FAULT clear delay after FAULT-Signal (T_{FLTCLR})
12	VSS	Logic ground
13	COM	Low side gate driver reference
28,24,20	VB1,2,3	High side positive power supply
27,23,19	HO1,2,3	High side gate driver output
26,22,18	VS1,2,3	High side negative power supply
16,15,14	LO1,2,3	Low side gate driver output

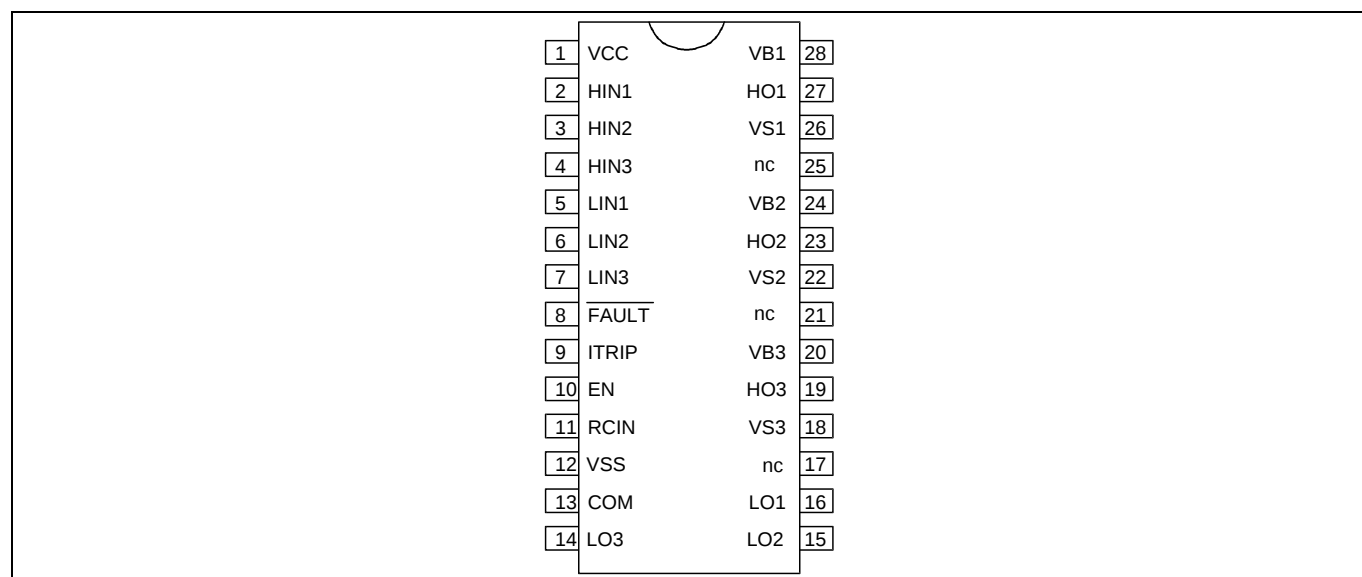


Figure 4 Pin Configuration of 6ED family (signals HIN1,2,3 and LIN1,2,3 according to Table 1)

3 Functional description

3.1 Low Side and High Side Control Pins (Pin 2, 3, 4, 5, 6, 7)

The Schmitt trigger input threshold of them is such to guarantee LSTTL and CMOS compatibility down to 3.3 V controller outputs. Input Schmitt trigger and noise filter provide beneficial noise rejection to short input pulses according to Figure 5 and Figure 6.

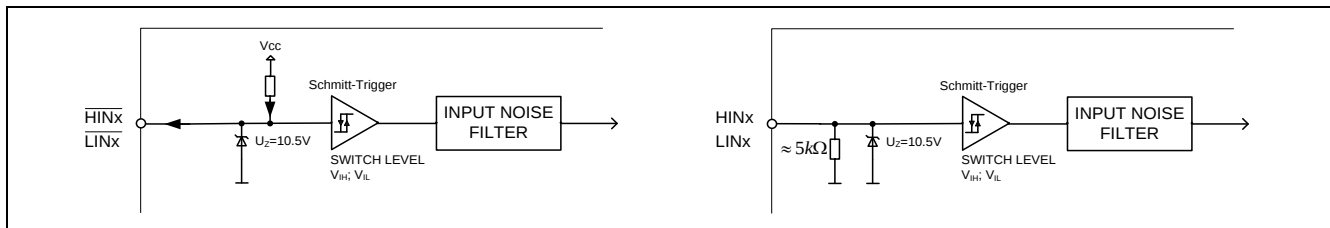


Figure 5 Input pin structure for negative logic (left) and positive logic (right)

An internal pull-up of about 75 kΩ (negative logic) pre-biases the input during supply start-up and a ESD zener clamp is provided for pin protection purposes. The zener diodes are therefore designed for single pulse stress only and not for continuous voltage stress over 10V. For versions with positive, a 5 kΩ pull-down resistor is used for this function.

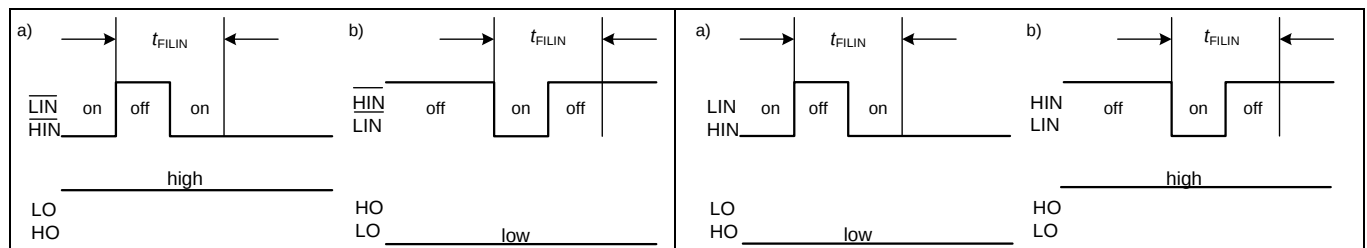


Figure 6 Input filter timing diagram for negative logic (left) and positive logic (right)

It is anyway recommended for proper work of the driver not to provide input pulse-width lower than 1 μs.

The 6ED family – 2nd generation provides additionally a shoot through prevention capability which avoids the simultaneous on-state of two channels of the same leg (i.e. HO1 and LO1, HO2 and LO2, HO3 and LO3). When two inputs of a same leg are activated, only one leg output is activated, so that the leg is kept steadily in a safe state.

A minimum dead time insertion of typ. 310 ns is also provided, in order to reduce cross-conduction of the external power switches.

3.2 EN (Gate Driver Enable, Pin 10)

The signal applied to pin EN controls directly the output stages. All outputs are set to LOW, if EN is at LOW logic level. The internal structure of the pin is given in Figure 7. The switching levels of the Schmitt-Trigger are here $V_{EN,TH+} = 2.1$ V and $V_{EN,TH-} = 1.3$ V. The typical propagation delay time is $t_{EN} = 780$ ns. There is an internal pull down resistor (75 kΩ), which keeps the gate outputs off in case of broken PCB connection.

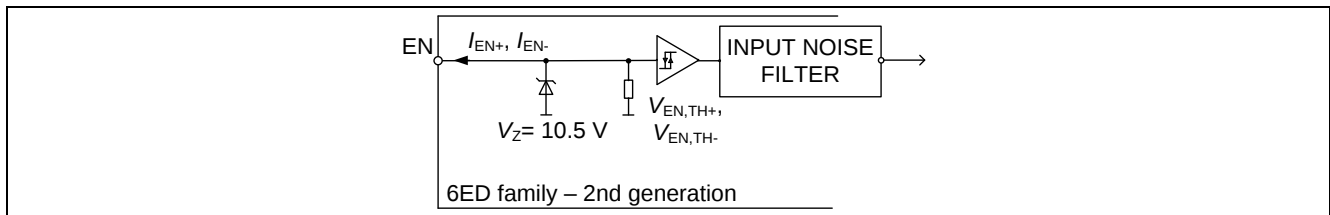


Figure 7 EN pin structures

3.3 /FAULT (Fault Feedback, Pin 8)

/Fault pin is an active low open-drain output indicating the status of the gate driver (see Figure 8). The pin is active (i.e. forces LOW voltage level) when one of the following conditions occur:

- Under-voltage condition of VCC supply: In this case the fault condition is released as soon as the supply voltage condition returns in the normal operation range (please refer to VCC pin description for more details).
- Over-current detection (ITRIP): The fault condition is latched until current trip condition is finished and RCIN input is released (please refer to ITRIP pin).

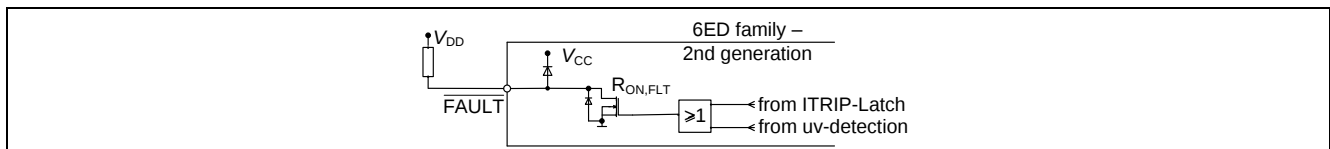


Figure 8 /FAULT pin structures

3.4 ITRIP and RCIN (Over-Current Detection Function, Pin 9, 11)

The 6ED family – 2nd generation provides an over-current detection function by connecting the ITRIP input with the motor current feedback. The ITRIP comparator threshold (typ 0.44 V) is referenced to VSS ground. An input noise filter (typ. $t_{ITRIPMIN} = 230$ ns) prevents the driver to detect false over-current events.

Over-current detection generates a hard shut down of all outputs of the gate driver and provides a latched fault feedback at /FAULT pin. RCIN input/output pin is used to determine the reset time of the fault condition. As soon as ITRIP threshold is exceeded the external capacitor connected to RCIN is fully discharged. The capacitor is then recharged by the RCIN current generator when the over-current condition is finished. As soon as RCIN voltage exceeds the rising threshold of typ $V_{RCIN,TH} = 5.2$ V, the fault condition releases and the driver returns operational following the control input pins according to Section 3.1.

3.5 VCC, VSS and COM (Low Side Supply, Pin 1, 12, 13)

VCC is the low side supply and it provides power both to input logic and to low side output power stage. Input logic is referenced to VSS ground as well as the under-voltage detection circuit. Output power stage is referenced to COM ground. COM ground is floating respect to VSS ground with a maximum range of operation of ± 5.7 V. A back-to-back zener structure protects grounds from noise spikes.

The under-voltage circuit enables the device to operate at power on when a typical supply voltage higher than V_{CCUV+} is present.

The IC shuts down all the gate drivers power outputs, when the VCC supply voltage is below $V_{CCUV-} = 9.8$ V respectively 8.1 V. This prevents the external power switches from critically low gate voltage levels during on-state and therefore from excessive power dissipation.

3.6 VB1, 2, 3 and VS1, 2, 3 (High Side Supplies, Pin 17, 19, 20, 22, 23, 25)

VB to VS is the high side supply voltage. The high side circuit can float with respect to VSS following the external high side power device emitter/source voltage. Due to the low power consumption, the floating driver stage can be supplied by bootstrap topology connected to VCC.

The device operating area as a function of the supply voltage is given in Figure 15 and Figure 16.

3.7 LO1,2,3 and HO1,2,3 (Low and High Side Outputs, Pin 14, 15, 16, 18, 21, 24)

Low side and high side power outputs are specifically designed for pulse operation such as gate drive of IGBT and MOSFET devices. Low side outputs (i.e. LO1,2,3) are state triggered by the respective inputs, while high side outputs (i.e. HO1,2,3) are edge triggered by the respective inputs. In particular, after an under voltage condition of the VBS supply, a new turn-on signal (edge) is necessary to activate the respective high side output, while after a under voltage condition of the VCC supply, the low side outputs switch to the state of their respective inputs.

4 Electrical parameters

4.1 Absolute maximum ratings

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ }^{\circ}\text{C}$.

Table 3 Absolute maximum ratings

Parameter	Symbol	Min.	Max.	Unit
High side offset voltage ¹	V_S	$V_{CC}-V_{BS}-6$	650	V
High side offset voltage ($t_p<500\text{ns}$) ¹		$V_{CC}-V_{BS}-50$	–	
High side offset voltage ¹	V_B	$V_{CC}-6$	670	
High side offset voltage ($t_p<500\text{ns}$) ¹		$V_{CC}-50$	–	
High side floating supply voltage (V_B vs. V_S) (internally clamped)	V_{BS}	-1	20	
High side output voltage (V_{HO} vs. V_S)	V_{HO}	-0.5	$V_B+0.5$	
Low side supply voltage (internally clamped)	V_{CC}	-1	20	
Low side supply voltage (V_{CC} vs. V_{COM})	V_{CCOM}	-0.5	25	
Gate driver ground	V_{COM}	-5.7	5.7	
Low side output voltage (V_{LO} vs. V_{COM})	V_{LO}	-0.5	$V_{CCOM}+0.5$	
Input voltage LIN,HIN,EN,ITRIP	V_{IN}	-1	10	
FAULT output voltage	V_{FLT}	-0.5	$V_{CC}+0.5$	
RCIN output voltage	V_{RCIN}	-0.5	$V_{CC}+0.5$	
Power dissipation (to package) ²	P_D	–	0.6	W
Thermal resistance (junction to ambient)	$R_{th(j-a)}$	–	165	K/W
Junction temperature	T_J	–	150	$^{\circ}\text{C}$
Storage temperature	T_S	-40	150	
offset voltage slew rate ³	dV_S/dt		50	V/ns

¹ In case $V_{CC} > V_B$ there is an additional power dissipation in the internal bootstrap diode between pins VCC and VBx. Insensitivity of bridge output to negative transient voltage up to -50 V is not subject to production test – verified by design / characterization.

² Consistent power dissipation of all outputs. All parameters inside operating range.

³ Not subject of production test, verified by characterisation

4.2 Required operation conditions

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ °C}$.

Table 4 Required Operation Conditions

Parameter		Symbol	Min.	Max.	Unit
High side offset voltage ¹	6EDL04x065xT	V_B	7	667.5	V
Low side supply voltage (V_{CC} vs. V_{COM})		V_{CCOM}	10	25	

4.3 Operating Range

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ °C}$.

Table 5 Operating range

Parameter		Symbol	Min.	Max.	Unit
High side floating supply offset voltage		V_S	$V_{CC} - V_{BS} - 1$	650	V
High side floating supply offset voltage (V_B vs. V_{CC} , statically)		V_{BCC}	-1.0	650	
High side floating supply voltage (V_B vs. V_S , Note 1)	6EDL04I065NT 6EDL04I065PT 6EDL04N065PT	V_{BS}	13 10	17.5 17.5	V
High side output voltage (V_{HO} vs. V_S)		V_{HO}	0	V_{BS}	
Low side output voltage (V_{LO} vs. V_{COM})		V_{LO}	0	V_{CC}	
Low side supply voltage	6EDL04I065NT 6EDL04I065PT 6EDL04N065PT	V_{CC}	13 10	17.5 17.5	
Low side ground voltage		V_{COM}	-2.5	2.5	
Logic input voltages LIN, HIN, EN, ITRIP ²		V_{IN}	0	5	
FAULT output voltage		V_{FLT}	0	V_{CC}	
RCIN input voltage		V_{RCIN}	0	V_{CC}	
Pulse width for ON or OFF ³		t_{IN}	1	–	µs
Ambient temperature		T_a	-40	105	°C

¹ Logic operational for V_B (V_B vs. V_S) > 7.0 V

² All input pins (HINx, LINx) and EN, ITRIP pin are internally clamped (see abs. maximum ratings)

³ In case of input pulse width at LINx and HINx below 1µ the input pulse may not be transmitted properly

Table 6 Static parameters

Parameter		Symbol	Values			Unit	Test condition
			Min.	Typ.	Max.		
V_{CC} and V_{BS} supply undervoltage lockout hysteresis	6EDL04I065NT	V_{CCUVH}	1.2	1.9	-	V	
	6EDL04I065PT	V_{BSUVH}					
	6EDL04N065PT		0.5	0.9	-		
High side leakage current betw. VS and VSS		I_{LVS+}		1	12.5	μA	$V_S = 650V$
High side leakage current betw. VS and VSS		I_{LVS+}^1	-	10	-		$T_J = 125^\circ C, V_S = 650V$
High side leakage current between VSx and VSy (x=1,2,3 and y=1,2,3)		I_{LVS-}^1	-	10	-		$T_J = 125^\circ C$ $V_{Sx} - V_{Sy} = 650V$
Quiescent current V_{BS} supply (VB only)		I_{QBS1}	-	210	400		HO=low
Quiescent current V_{BS} supply (VB only)		I_{QBS2}	-	210	400		HO=high
Quiescent current V_{CC} supply (VCC only)	6EDL04I065NT	I_{QCC1}	-	1.1	1.8	mA	$V_{LIN} = \text{float. (all)}$ $V_{VSx} = 50V$ (only bootstrap types)
	6EDL04I065PT		-	0.75	1.5		
	6EDL04N065PT						
Quiescent current V_{CC} supply (VCC only)	6EDL04I065NT	I_{QCC2}	-	1.3	2		$V_{LIN} = 0, V_{HIN} = 3.3 V$ $V_{VSx} = 50V$
	6EDL04I065PT			0.75	1.5		$V_{LIN} = 3.3 V, V_{HIN} = 0$ $V_{VSx} = 50V$
	6EDL04N065PT						
Quiescent current V_{CC} supply (VCC only)	6EDL04I065NT	I_{QCC3}	-	1.3	2		$V_{LIN} = 3.3 V, V_{HIN} = 0$ $V_{VSx} = 50V$
	6EDL04I065PT			0.75	1.5		$V_{LIN} = 0, V_{HIN} = 3.3 V$ $V_{VSx} = 50V$
	6EDL04N065PT						
Input bias current	6EDL04I065NT	I_{LIN+}	-	70	100	μA	$V_{LIN} = 3.3 V$
	6EDL04I065PT		400	700	1100		
	6EDL04N065PT						
Input bias current	6EDL04I065NT	I_{LIN-}	-	110	200	μA	$V_{LIN} = 0$
	6EDL04I065PT			0			
	6EDL04N065PT						
Input bias current	6EDL04I065NT	I_{HIN+}	-	70	100	μA	$V_{HIN} = 3.3 V$
	6EDL04I065PT		400	700	1100		
	6EDL04N065PT						
Input bias current	6EDL04I065NT	I_{HIN-}	-	110	200	μA	$V_{HIN} = 0$
	6EDL04I065PT			0			
	6EDL04N065PT						
Input bias current (ITRIP=high)		I_{ITRIP+}		45	120	μA	$V_{ITRIP} = 3.3 V$
Input bias current (EN=high)		I_{EN+}	-	45	120		$V_{ENABLE} = 3.3 V$
Input bias current RCIN (internal current source)		I_{RCIN}		2.8			$V_{RCIN} = 2 V$
Mean output current for load capacity charging in range from 3 V (20%) to 6 V (40%)		I_{O+}	120	165	-	mA	$C_L = 10 nF$

¹ Not subject of production test, verified by characterisation

Table 6 Static parameters

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
Peak output current turn on (single pulse)	I_{Opk+}^1		240			$R_L = 0 \Omega, t_p < 10 \mu s$
Mean output current for load capacity discharging in range from 12 V (80%) to 9 V (60%)	I_{O-}	250	375	-		$C_L = 10 \text{ nF}$
Peak output current turn off (single pulse)	I_{Opk-}^1		420			$R_L = 0 \Omega, t_p < 10 \mu s$
Bootstrap diode forward voltage between VCC and VB	$V_{F,BSD}$	-	1.0	1.3	V	$I_F = 0.5 \text{ mA}$
Bootstrap diode forward current between VCC and VB	$I_{F,BSD}$	40	65	90	mA	$V_F = 4 \text{ V}$
Bootstrap diode resistance	R_{BSD}	24	40	60	Ω	$V_{F1} = 4 \text{ V}, V_{F2} = 5 \text{ V}$
RCIN low on resistance of the pull down transistor	$R_{on,RCIN}$	-	40	100		$V_{RCIN} = 0.5 \text{ V}$
FAULT low on resistance of the pull down transistor	$R_{on,FLT}$	-	45	100		$V_{FAULT} = 0.5 \text{ V}$

4.6 Dynamic parameters

$V_{CC} = V_{BS} = 15 \text{ V}$, $V_S = V_{SS} = V_{COM}$ unless otherwise specified. All parameters are valid for $T_a = 25^\circ \text{C}$.

Table 7 Dynamic parameters

Parameter		Symbol	Values			Unit	Test condition
			Min.	Typ.	Max.		
Turn-on propagation delay		t_{on}	360	490	760	ns	$V_{LIN/HIN} = 0 \text{ or } 3.3 \text{ V}$
Turn-off propagation delay	6EDL04I065NT 6EDL04I065PT	t_{off}	360	490	760		
	6EDL04N065PT		400	530	800		
Turn-on rise time		t_r	-	60	100		$V_{LIN/HIN} = 0 \text{ or } 3.3 \text{ V}$
Turn-off fall time		t_f	-	26	45		$C_L = 1 \text{ nF}$
Shutdown propagation delay ENABLE		t_{EN}	-	780	1100		$V_{EN} = 0$
Shutdown propagation delay ITRIP		t_{ITRIP}	400	670	1000		$V_{ITRIP} = 1 \text{ V}$
Input filter time ITRIP		$t_{ITRIPMIN}$	155	230	380		$V_{LIN/HIN} = 0 \text{ \& } 3.3 \text{ V}$
Propagation delay ITRIP to FAULT		t_{FLT}	-	420	700		
Input filter time at LIN/HIN for turn on and off		t_{FILIN}	120	300	-		
Input filter time EN		t_{FILEN}	300	600	-	ms	$V_{LIN/HIN} = 0 \text{ \& } 3.3 \text{ V}$ $V_{ITRIP} = 0$
Fault clear time at RCIN after ITRIP-fault, ($C_{RCIN} = 1 \text{ nF}$)		t_{FLTCLR}	1.0	1.9	4.0		

¹ Not subject of production test, verified by characterisation

Table 7 Dynamic parameters

Parameter		Symbol	Values			Unit	Test condition
			Min.	Typ.	Max.		
Dead time		DT	150	310	-	ns	$V_{LIN/HIN} = 0 \text{ \& } 3.3 \text{ V}$
Matching delay ON, max(ton)-min(ton), ton are applicable to all 6 driver outputs		MT _{ON}	-	20	100		external dead time > 500 ns
Matching delay OFF, max(toff)-min(toff), toff are applicable to all 6 driver outputs		MT _{OFF}	-	40	100		external dead time > 500 ns
Output pulse width matching. $PW_{in}-PW_{out}$	6EDL04I065NT 6EDL04I065PT	PM		40	100		$PW_{in} > 1 \text{ }\mu\text{s}$
	6EDL04N065PT			10	100		

5 Timing diagrams

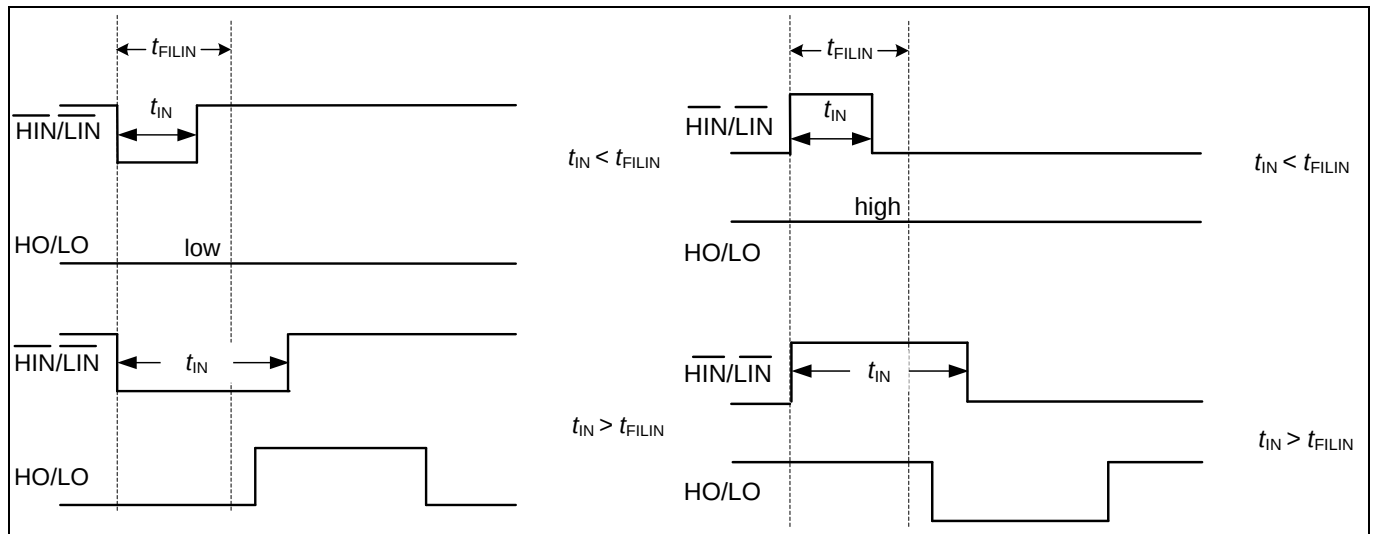


Figure 9 Timing of short pulse suppression (6EDL04I065NT)

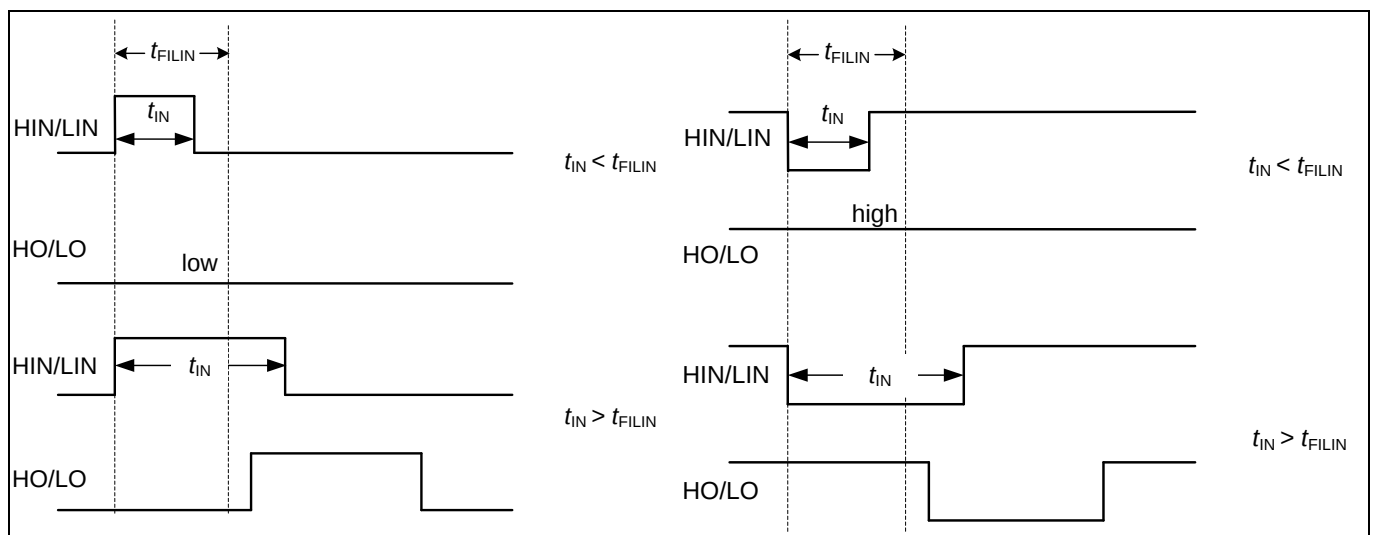


Figure 10 Timing of short pulse suppression (6EDL04I065PT and 6EDL04N065PT)

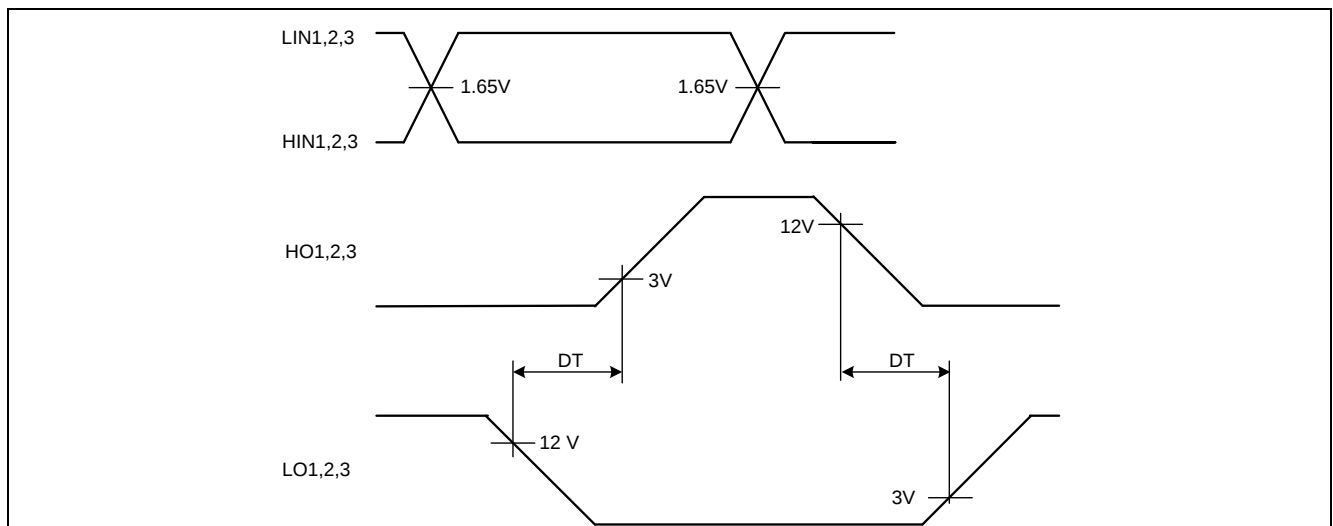


Figure 11 Timing of internal deadtime (input logic according to Table 1)

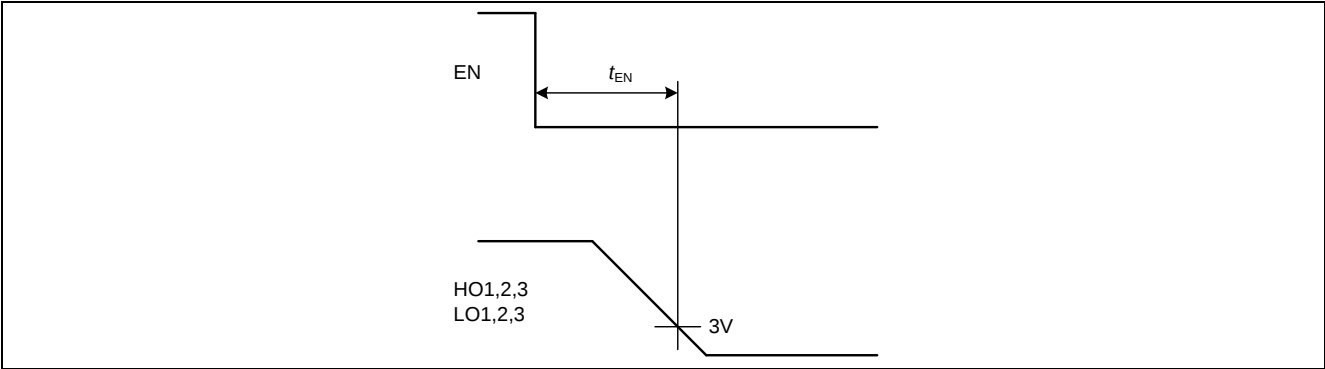


Figure 12 Enable delay time definition

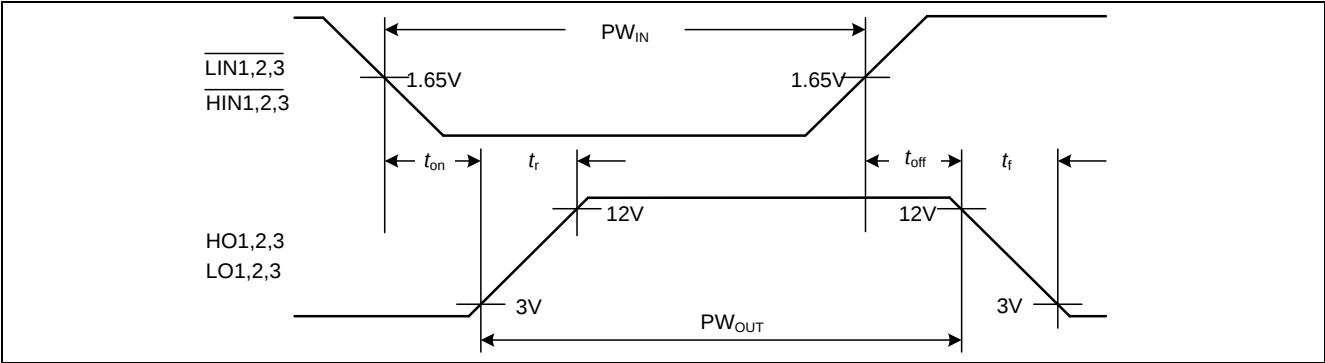


Figure 13 Input to output propagation delay times and switching times definition (6EDL04I065NT)

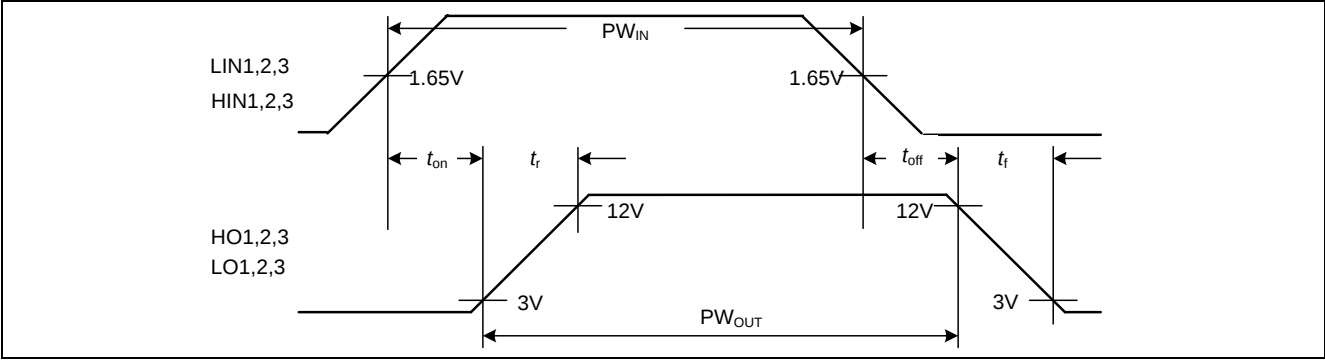


Figure 14 Input to output propagation delay times and switching times definition (6EDL04I065PT and 6EDL04N065PT)

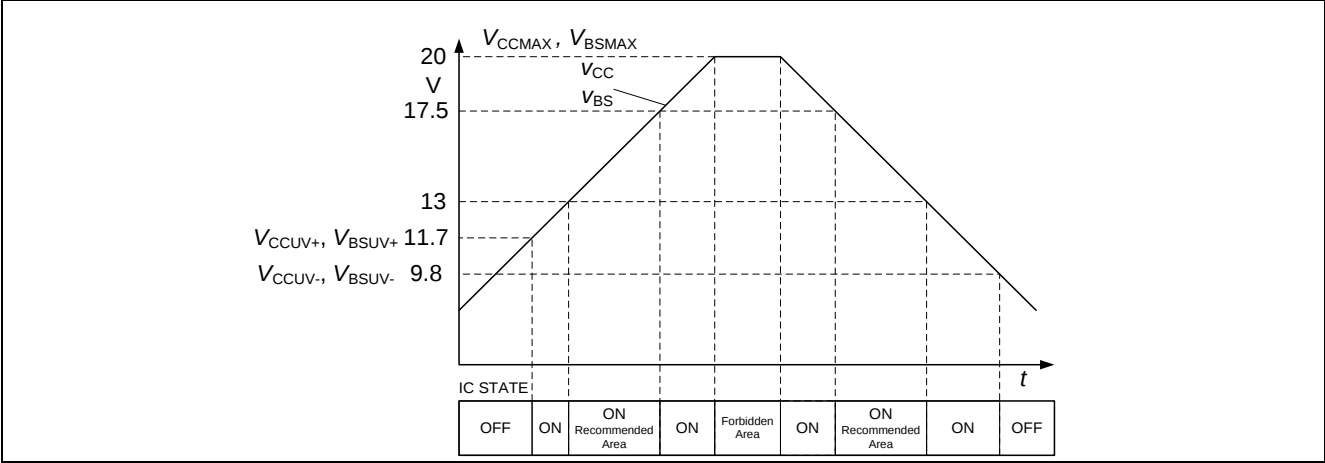


Figure 15 Operating areas (6EDL04I065NT, 6EDL04I065PT)

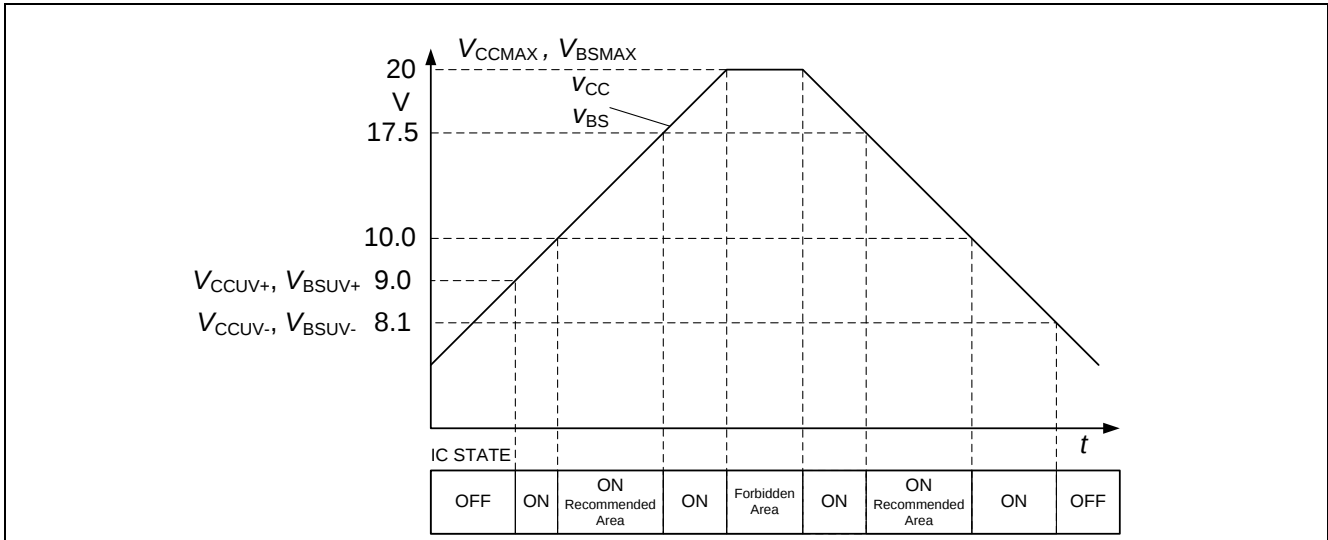


Figure 16 Operating Areas (6EDL04N065PT)

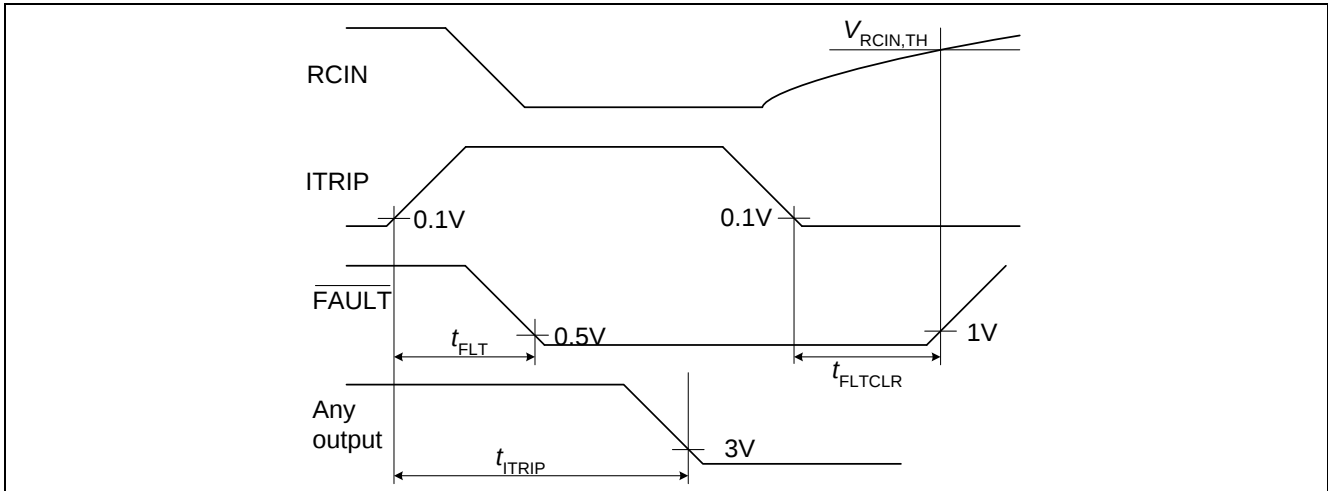


Figure 17 ITRIP-Timing

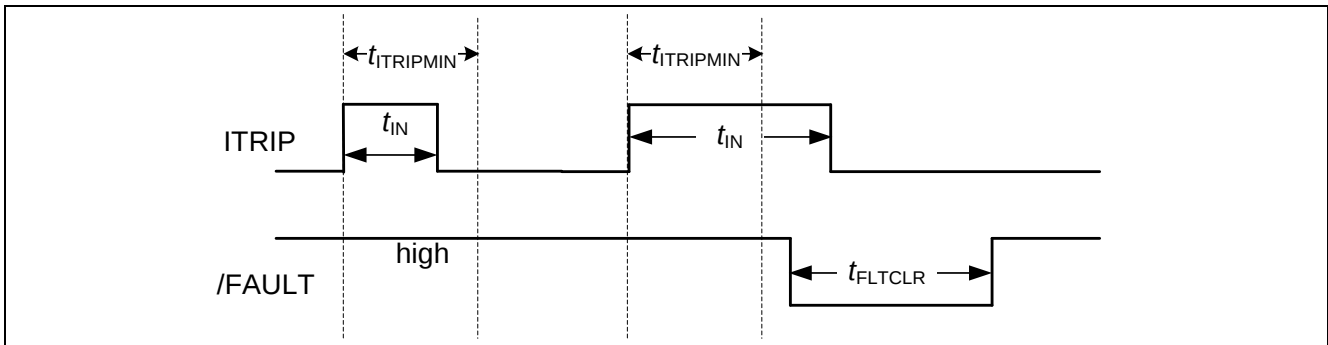


Figure 18 ITRIP Input Timing

6 Qualification information¹

Table 8 Qualification information

Qualification level		Industrial ²
		Note: This family of ICs has passed JEDEC's Industrial qualification. Consumer qualification level is granted by extension of the higher Industrial level.
Moisture sensitivity level		MSL3 ³ , 260°C (per IPC/JEDEC J-STD-020)
ESD	Charged device model	Class C3 (1.0 kV) (per ANSI/ESDA/JEDEC JS-002-2018)
	Human body model	Class 2 (2.0 kV) (per ANSI/ESDA/JEDEC JS-001-2017)
RoHS compliant		Yes

¹ Qualification standards can be found at Infineon's web site www.infineon.com

² Higher qualification ratings may be available should the user have such requirements. Please contact your Infineon sales representative for further information.

³ Higher MSL ratings may be available for the specific package types listed here. Please contact your Infineon sales representative for further information.

7 Related products

Table 9

Gate Driver ICs	
2EDL05I06 / 2EDL05N06	600 V, half-bridge thin-film SOI level shift gate driver with integrated high speed, low $R_{DS(ON)}$ bootstrap diode, 0.36/0.7 A source/sink current driver, 8pins/14pins package, for MOSFET or IGBT.
2EDL23I06 / 2EDL23N06	600 V, half-bridge thin-film SOI level shift gate driver with integrated high speed, low $R_{DS(ON)}$ bootstrap diode, with over-current protection (OCP), 2.3/2.8 A source/sink current driver, and one pin Enable/Fault function for MOSFET or IGBT.
Power Switches	
IKD06N60RC2	600 V, 6 A IGBT Discrete with Reverse Conducting Drive 2-diode in TO-252 package
IPN60R1K0PFD7S	600V CoolMOS™ PFD7 superjunction MOSFET in SOT-223
iMOTION™ Controllers	
IRMCK099	iMOTION™ Motor control IC for variable speed drives utilizing sensor-less Field Oriented Control (FOC) for Permanent Magnet Synchronous Motors (PMSM).
IMC101T	High performance Motor Control IC for variable speed drives based on field oriented control (FOC) of permanent magnet synchronous motors (PMSM).

8 Package information

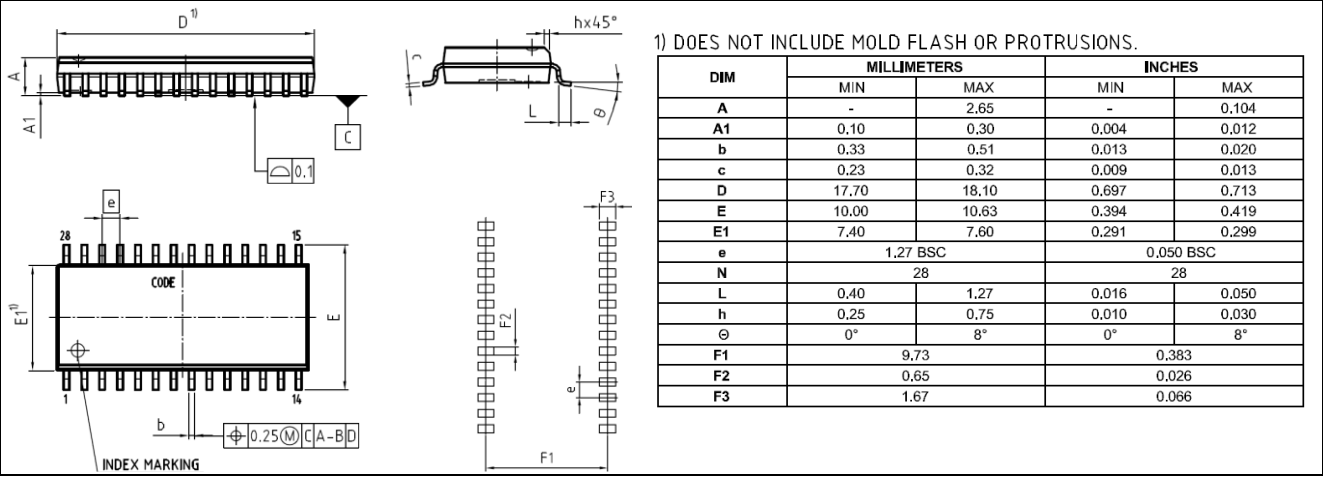


Figure 19 Package drawing

9 Part marking information

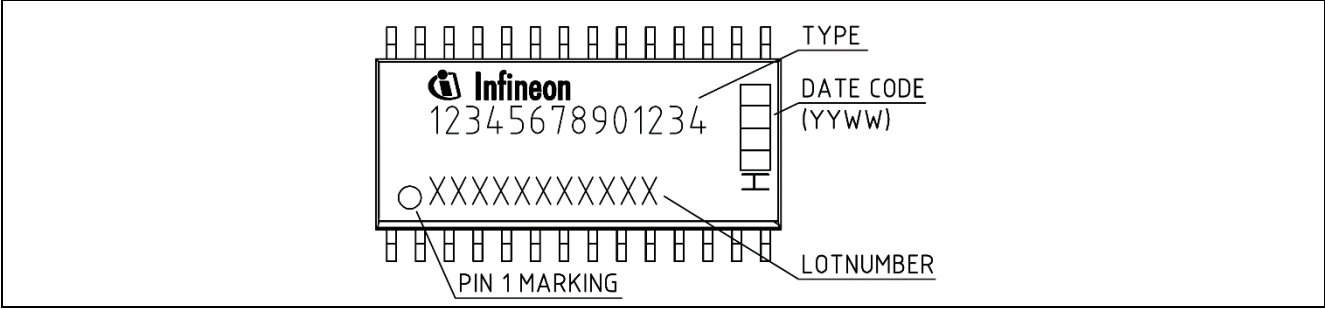


Figure 20 Package drawing

10 Additional documentation and resources

Several technical documents related to the use of HVICs are available at www.infineon.com; use the Site Search function and the document number to quickly locate them. Below is a short list of some of these documents.

Application Notes:

[Understanding HVIC Datasheet Specifications](#)

[HV Floating MOS-Gate Driver ICs](#)

[Use Gate Charge to Design the Gate Drive Circuit for Power MOSFETs and IGBTs](#)

[Bootstrap Network Analysis: Focusing on the Integrated Bootstrap Functionality](#)

Design Tips:

[Using Monolithic High Voltage Gate Drivers](#)

[Alleviating High Side Latch on Problem at Power Up](#)

[Keeping the Bootstrap Capacitor Charged in Buck Converters](#)

[Managing Transients in Control IC Driven Power Stages](#)

[Simple High Side Drive Provides Fast Switching and Continuous On-Time](#)

10.1 Infineon online forum resources

The Gate Driver Forum is live at Infineon Forums (www.infineonforums.com). This online forum is where the Infineon gate driver IC community comes to the assistance of our customers to provide technical guidance – how to use gate drivers ICs, existing and new gate driver information, application information, availability of demo boards, online training materials for over 500 gate driver ICs. The Gate Driver Forum also serves as a repository of FAQs where the user can review solutions to common or specific issues faced in similar applications.

Register online at the Gate Driver Forum and learn the nuances of efficiently driving a power switch in any given power electronic application.



11 Revision history

Document version	Date of release	Description of changes
2.0	2024-04-17	Final datasheet.

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